

环境对应

Conforming to Environmental

◆对应RoHS管理物质/Conforming to RoHS Directive

品种 TYPE	铝电解电容器 Aluminum Electrolytic Capacitors				塑胶薄膜电容器 Film Capacitors		导电性高分子铝固体 电解电容器 Conductive Polymer Aluminum Solid Electrolytic Capacitors (PC-CON)	薄膜高分子积 层电容器 Polymer Multi-Layer Capacitors (PMLCAP [®])	双电层电容器 Electric Double Layer Capacitors	
	贴片型 SMD Type	引线型 Lead Wire Type	基板自立型 Snap-in type	螺栓端子型 Screw terminal type	金属熔射型 Metallized Type	箔电极型 Foil type	贴片型 SMD Type	贴片型 SMD Type	引线型 Lead Wire Type	螺栓端子型 Screw terminal type
对应RoHS指令 RoHS Compliance	对应完毕/Complied									
铅 Lead	不含/Not Contain									
镉 Cadmium	不含/Not Contain									
水银 Mercury	不含/Not Contain									
六价铬 Chrome (VI)	不含/Not Contain(*1)									
PBB	不含/Not Contain									
PBDE	不含/Not Contain									
RoHS对应品 的标示 Identification fo RoHS Compliance pats	内外包装的标签上标示有RoHS Compliance Add"RoHS Compliance"marking on inner and outer carton label									

*1:螺栓端子型的固定带:三价铬镀层/Band of Screw terminal type:Chromium(III)

◆端子材质、焊接/Terminal material, Soldering

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端子材料 Terminal material	(∞ Φ10) Fe/Cu/Sn-0.5Bi	Fe/Cu/Sn		铝 Aluminum	Fe/Cu/Sn or Cu/Sn	Fe/Cu/Sn	Ni/Pd/Au 镀层 plating	Sn 镀层 Sn plating	Fe/Cu/Sn	铝 Aluminum
焊接耐热性 Resistance to soldering heat	请参照[回流焊 允许条件] Please find"Reflow Soldering Condition"	260℃波峰焊 260℃ FLOW Soldering		焊接对象外 Not applicable	请参照[焊接作业] Please find"Soldering Operation		260℃ 回流焊 260℃ Reflow	260℃回流焊 260℃ Reflow	260℃波峰焊 260℃ FLOW Soldering	焊接对象外 Not applicable

◆关于遵守欧洲REACH规定/Regarding compliance to European REACH Regulation

根据2008年5月26日发布的RIP3.8TGD (Technical Guidance Document)的内容, 本公司制造的电子部件为“无意图发放的成品”

因此不适用欧洲REACH规定的第七条第1项的“注册”条款

According to the content of RIP3.8TGD (Technical Guidance Document) which is published on 26 May 2008, our electronic components are "articles without any intended release". Therefore they are not applicable for "Registration" for European REACH Regulation Article 7(1)